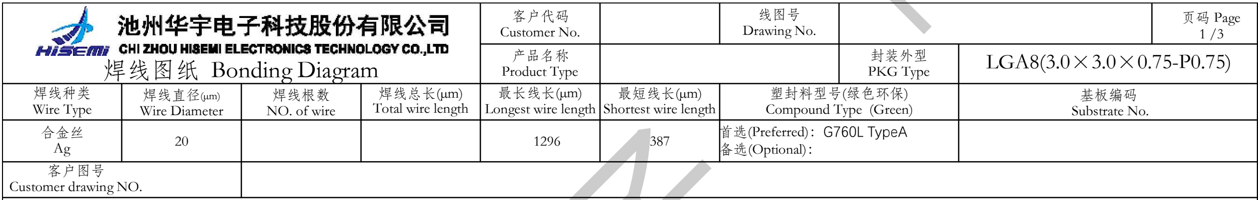
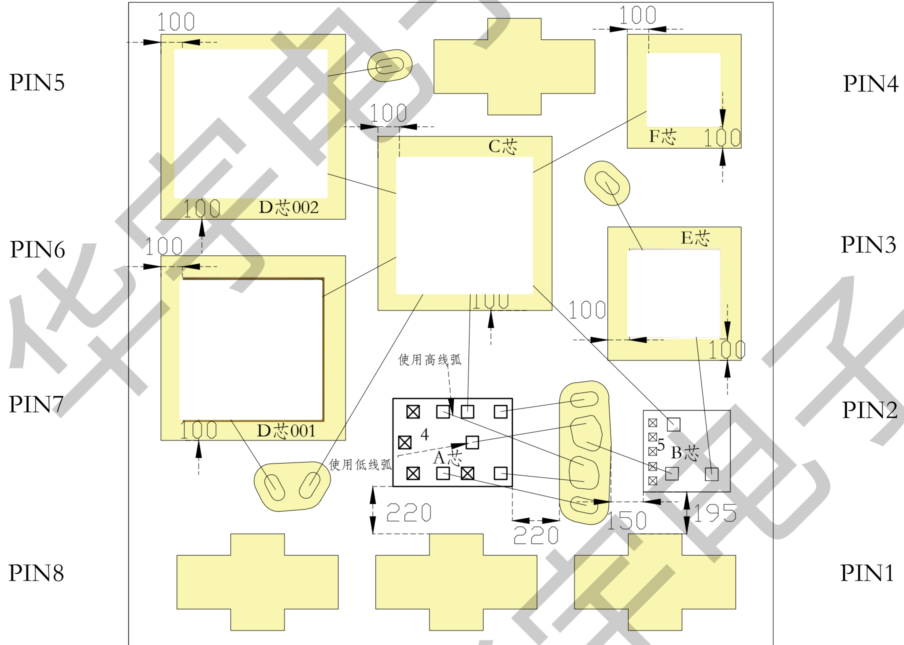
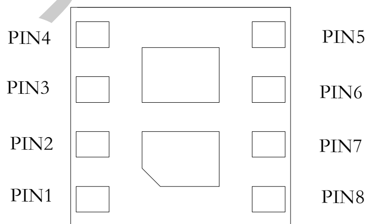


池州华宇电子科技股份有限公司 CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD 焊线图纸 Bonding Diagram				客户代码 Customer No.		线图号 Drawing No.		页码 Page 1 /3
				产品名称 Product Type			封装外型 PKG Type	LGA8(3.0×3.0×0.75-P0.75)
焊线种类 Wire Type	焊线直径(µm) Wire Diameter	焊线根数 NO. of wire	焊线总长(µm) Total wire length	最长线长(µm) Longest wire length	最短线长(µm) Shortest wire length	塑封料型号(绿色环保) Compound Type (Green)		基板编码 Substrate No.
合金丝 Ag	20			1296	387	首选(Preferred)：G760L TypeA 备选(Optional)：		
客户图号 Customer drawing NO.								

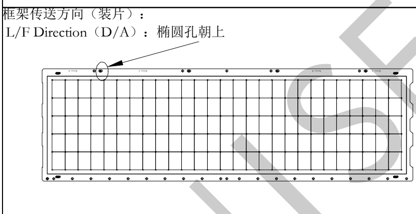


注意：C芯，F芯装片不区分方向。

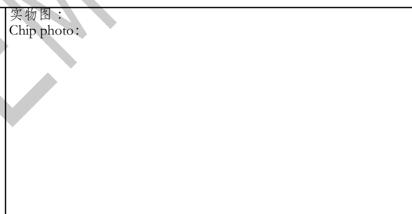


底部示意图

框架传送方向（装片）：
L/F Direction（D/A）：椭圆孔朝上



实物图：
Chip photo：



特殊说明 Special Instructions：

DB注意：
1.装片位置公差为±30um；
2.D芯002由D芯001顺时针旋转90°。
3.控制溢胶，为WB预留焊线位置。

WB注意：
数字为不打线pad点个数。

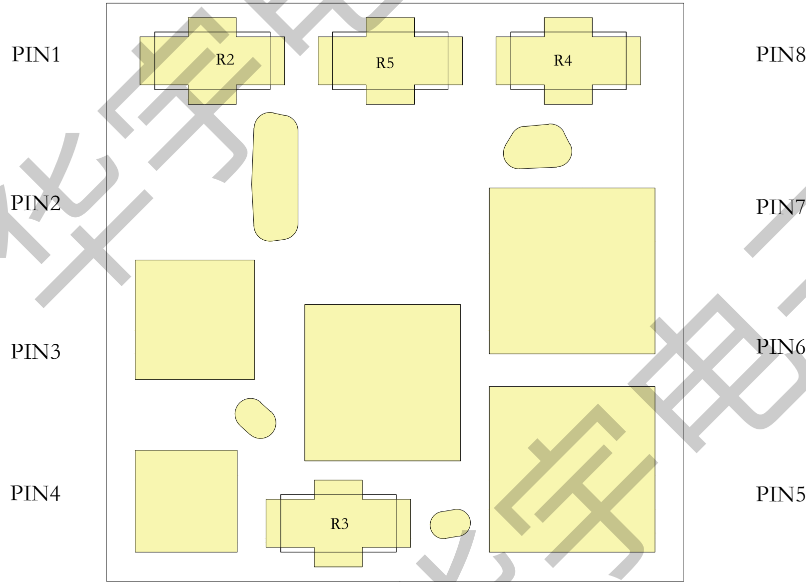
说明 Instructions	粘片胶类型 epoxy type	芯片名称 Die name	芯片尺寸 Die Size	最小焊盘尺寸 Min BPO (µm²)	最小焊盘间距 Min BPP(µm)	铝垫厚度(µm) Pad Thickness	焊盘下是否有电路 Circuit under Pad	划片道宽度 Street line (µm)	晶圆尺寸 Wafer Size	是否激光切割 If laser ?	减薄厚度(µm) Wafer Thickness
A芯：DIE A	绝缘胶 (Non-conductive) S801-3		555*410（µm²）21.85*16.14(mil²)	57*57	110	2.7	否/N0	70	8	否/N0	160
B芯：DIE B	绝缘胶 (Non-conductive) S801-3		405*380（µm²）15.94*14.96(mil²)	60*60	100	2.7	否/N0	60	8	否/N0	200
C芯：DIE C	导电胶 (conductivity) 6389		610*610（µm²）24.02*24.02(mil²)	530*530	100	2.9	否/N0	50	6	否/N0	275 来料厚度
D芯：DIE D	导电胶 (conductivity) 6389		660*660（µm²）25.98*25.98(mil²)	163*154	100	3.5	否/N0	50	5	否/N0	210 来料厚度
E芯：DIE E	导电胶 (conductivity) 6389		420*420（µm²）16.54*16.54(mil²)	93*93	100	3.5	否/N0	50	6	否/N0	210 来料厚度
F芯：DIE F	导电胶 (conductivity) 6389		330*330（µm²）12.99*12.99(mil²)	180*180	100	2.5	否/N0	50	5	否/N0	200 来料厚度
G芯：DIE G											

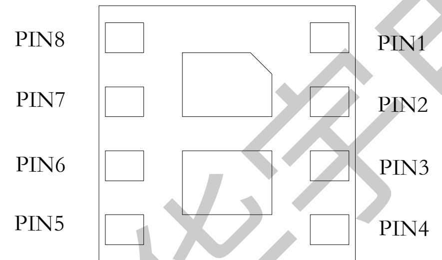
拟制 Prepared by		制图日期 Create Date		生效日期 Effective Date		客户确认签字/盖章：Customer Signature
研发审核 R&d check		产品工程审核 Product engineering check		批准 Approved by		

*温馨提示：图纸为产品下线生产的唯一依据，请您认真确认，我司依据您回签后的图纸生产，如图纸错误会产生不可估量损失，谢谢！
*warm tips: the drawing is the only basis for the production of the product. Please confirm it carefully. Our company will produce the drawings according to the drawings you have signed back, such as drawing mistakes, which will produce inestimable loss. Thank you

HISEMI 华宇电子

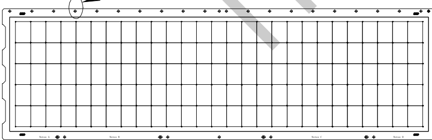
池州华宇电子科技股份有限公司 CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD 焊线图纸 Bonding Diagram	客户代码 Customer No.		线图号 Drawing No.		页码 Page 2/ 3
	产品名称 Product Type		封装外型 PKG Type	LGA8(3.0×3.0×0.75-P0.75)	





底部示意图

框架传送方向（装片）：
L/F Direction（D/A）：圆孔朝上



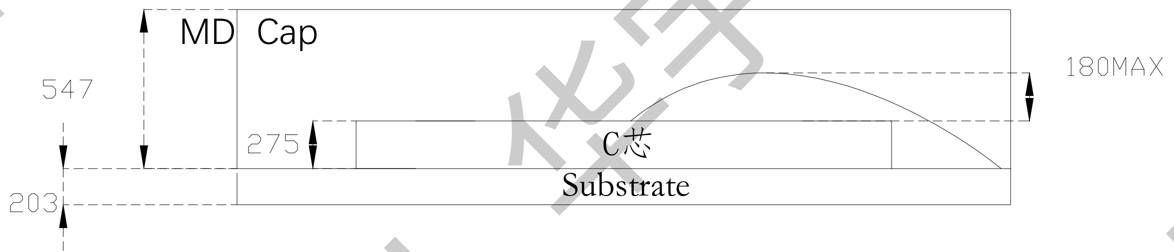
NO.	Item	Reference	value	package	KD P/N	Quantity
1	片式电阻	R2	1 kΩ ±1% 0.05W, 1/20W		01.01.01.KG10777006	1
2	片式电阻	R3	2 kΩ ±1% 0.05W, 1/20W		01.01.01.KG10777007	1
3	片式电阻	R4	390 Ω ±1% 0.05W, 1/20W		01.01.01.KG10777008	1
4	片式电阻	R5	6.8 kΩ ±1% 0.05W, 1/20W		01.01.01.KG10777009	1
5	基板	substrate	基板	/	LGA8(030030)777001	1
6	锡膏	/	F590 SnCu0.7-89M4	/		/
	SMT元器件总计					4

拟制 Prepared by		制图日期 Create Date		生效日期 Effective Date		客户确认签字/盖章: Customer Signature
研发审核 R&d check		产品工程审核 Product engineering check		批准 Approved by		

*温馨提示：图纸为产品下线生产的唯一依据，请您认真确认，我司依据您回签后的图纸生产，如图纸错误会产生不可估量损失，谢谢！
*warm tips: the drawing is the only basis for the production of the product. Please confirm it carefully. Our company will produce the drawings according to the drawings you have signed back, such as drawing mistakes, which will produce inestimable loss. Thank you

HISEMI 华宇电子

池州华宇电子科技股份有限公司 CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD 焊线图纸 Bonding Diagram	客户代码 Customer No.		线图号 Drawing No.		页码 Page 3/3
	产品名称 Product Type		封装外型 PKG Type	LGA8(3.0×3.0×0.75-P0.75)	



拟制 Prepared by		制图日期 Create Date		生效日期 Effective Date		客户确认签字/盖章: Customer Signature
研发审核 R&d check		产品工程审核 Product engineering check		批准 Approved by		

*温馨提示：图纸为产品下线生产的唯一依据，请您认真确认，我司依据您回签后的图纸生产，如图纸错误会产生不可估量损失，谢谢！
*warm tips: the drawing is the only basis for the production of the product. Please confirm it carefully. Our company will produce the drawings according to the drawings you have signed back, such as drawing mistakes, which will produce inestimable loss. Thank you

HISEMI 华宇电子